

### NCE N-Channel Enhancement Mode Power MOSFET

### **Description**

The NCE30ND35Q uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### **General Features**

V<sub>DS</sub> =30V,I<sub>D</sub> =35A

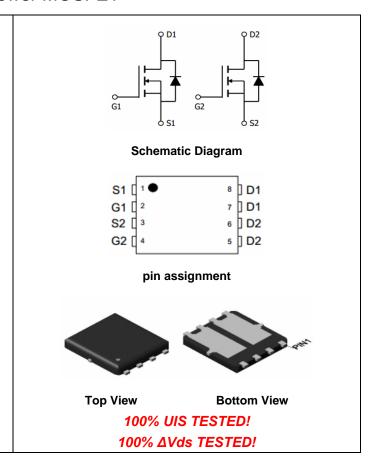
 $R_{DS(ON)}$  <13m $\Omega$  @  $V_{GS}$ =10V

 $R_{DS(ON)}$  <19m $\Omega$  @  $V_{GS}$ =4.5V

- High density cell design for ultra low Rdson
- Fully characterized Avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

### **Application**

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply



### **Package Marking and Ordering Information**

| Device Marking | Device     | Device Package | Reel Size | Tape width | Quantity |
|----------------|------------|----------------|-----------|------------|----------|
| NCE30ND35Q     | NCE30ND35Q | DFN3.3X3.3-8L  | -         | -          | -        |

### Absolute Maximum Ratings (T<sub>C</sub>=25℃unless otherwise noted)

| Parameter                                        | Symbol                | Limit      | Unit       |
|--------------------------------------------------|-----------------------|------------|------------|
| Drain-Source Voltage                             | V <sub>DS</sub>       | 30         | V          |
| Gate-Source Voltage                              | V <sub>G</sub> s      | ±20        | V          |
| Drain Current-Continuous                         | I <sub>D</sub>        | 35         | А          |
| Drain Current-Continuous(T <sub>C</sub> =100°C)  | I <sub>D</sub> (100℃) | 24.8       | Α          |
| Pulsed Drain Current                             | I <sub>DM</sub>       | 140        | Α          |
| Maximum Power Dissipation                        | P <sub>D</sub>        | 30         | W          |
| Derating factor                                  |                       | 0.24       | W/℃        |
| Single pulse avalanche energy (Note 5)           | E <sub>AS</sub>       | 72         | mJ         |
| Operating Junction and Storage Temperature Range | $T_{J}, T_{STG}$      | -55 To 150 | $^{\circ}$ |

### **Thermal Characteristic**

| Thermal Resistance, Junction-to-Case (Note 2) | $R_{	heta JC}$ | 4.17 | °C/W |  |
|-----------------------------------------------|----------------|------|------|--|

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# Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

| Parameter                          | Symbol              | Condition                                             | Min          | Тур        | Max       | Unit     |
|------------------------------------|---------------------|-------------------------------------------------------|--------------|------------|-----------|----------|
| Off Characteristics                |                     |                                                       |              |            |           |          |
| Drain-Source Breakdown Voltage     | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =250μA             | 30           | -          | -         | V        |
| Zero Gate Voltage Drain Current    | I <sub>DSS</sub>    | V <sub>DS</sub> =30V,V <sub>GS</sub> =0V              | -            | -          | 1         | μA       |
| Gate-Body Leakage Current          | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V             | -            | -          | ±100      | nA       |
| On Characteristics (Note 3)        |                     |                                                       |              |            |           |          |
| Gate Threshold Voltage             | $V_{GS(th)}$        | $V_{DS}=V_{GS}$ , $I_{D}=250\mu A$                    | 0.9          | 1.3        | 2.0       | V        |
| Drain-Source On-State Resistance   | D                   | V <sub>GS</sub> =10V, I <sub>D</sub> =20A             | -            | 11         | 13        | 13 mΩ    |
| Drain-Source On-State Resistance   | R <sub>DS(ON)</sub> | V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A            | -            | 14.5       | 19        | mΩ       |
| Forward Transconductance           | <b>g</b> FS         | V <sub>DS</sub> =5V,I <sub>D</sub> =20A               | 26           | -          | -         | S        |
| Dynamic Characteristics (Note4)    |                     |                                                       |              |            |           |          |
| Input Capacitance                  | C <sub>lss</sub>    | \/ -15\/\/ -0\/                                       | 800          | 1000       | 1500      | PF       |
| Output Capacitance                 | Coss                |                                                       | -            | 180.8      | -         | PF       |
| Reverse Transfer Capacitance       | C <sub>rss</sub>    | F=1.0MHz - 164.4                                      | -            | PF         |           |          |
| Switching Characteristics (Note 4) | ·                   |                                                       |              |            |           |          |
| Turn-on Delay Time                 | t <sub>d(on)</sub>  |                                                       | -            | 5          | -         | nS       |
| Turn-on Rise Time                  | t <sub>r</sub>      | $V_{DD}$ =15V, $R_L$ =0.75 $\Omega$                   | -            | 12         | -         | nS       |
| Turn-Off Delay Time                | $t_{d(off)}$        | $\begin{array}{c ccccccccccccccccccccccccccccccccccc$ | -            | nS         |           |          |
| Turn-Off Fall Time                 | t <sub>f</sub>      |                                                       | -            | 6          | -         | nS       |
| Total Gate Charge                  | Qg                  | \/ -45\/  -20A                                        | -            | 17         |           | nC       |
| Gate-Source Charge                 | $Q_{gs}$            | ,                                                     | -            | 2.8        |           | nC       |
| Gate-Drain Charge                  | $Q_{gd}$            | $\begin{array}{c ccccccccccccccccccccccccccccccccccc$ |              | nC         |           |          |
| Drain-Source Diode Characteristics | ·                   |                                                       |              |            |           |          |
| Diode Forward Voltage (Note 3)     | V <sub>SD</sub>     | V <sub>GS</sub> =0V,I <sub>S</sub> =20A               | -            |            | 1.2       | V        |
| Diode Forward Current (Note 2)     | I <sub>S</sub>      |                                                       | -            | -          | 35        | Α        |
| Reverse Recovery Time              | t <sub>rr</sub>     | TJ = 25°C, I <sub>F</sub> =20A                        | -            | 19         | -         | nS       |
| Reverse Recovery Charge            | Qrr                 | di/dt = 100A/µs <sup>(Note3)</sup>                    | -            | 10         | -         | nC       |
| Forward Turn-On Time               | t <sub>on</sub>     | Intrinsic turn-on time is negl                        | igible (turr | n-on is do | minated b | y LS+LD) |
| -                                  |                     |                                                       |              |            |           |          |

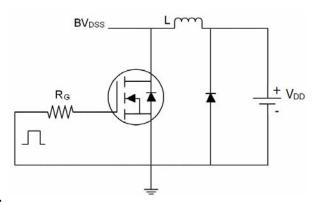
### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width ≤  $300\mu$ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

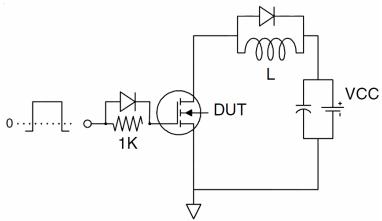


# **Test circuit**

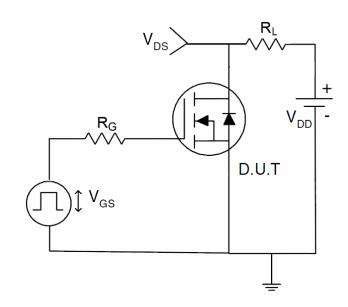
### 1) E<sub>AS</sub> test Circuits



### 2) Gate charge test Circuit:

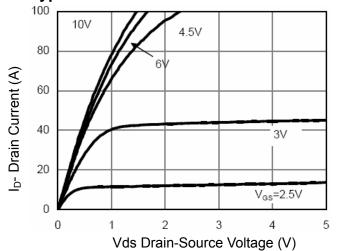


### 3) Switch Time Test Circuit:

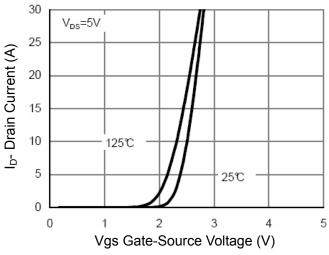




### **Typical Electrical and Thermal Characteristics (Curves)**



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

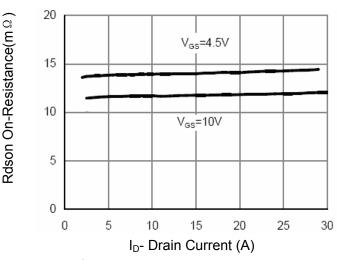
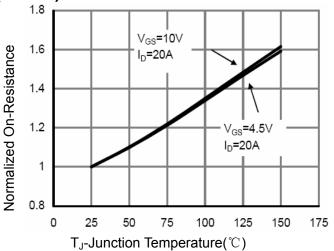
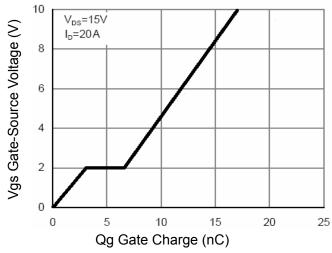


Figure 3 Rdson- Drain Current



**Figure 4 Rdson-Junction Temperature** 



**Figure 5 Gate Charge** 

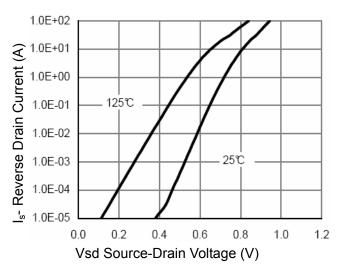


Figure 6 Source- Drain Diode Forward



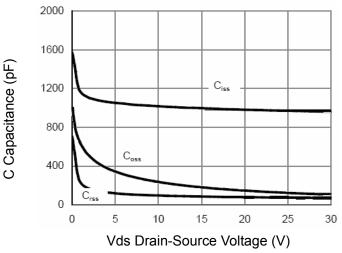


Figure 7 Capacitance vs Vds

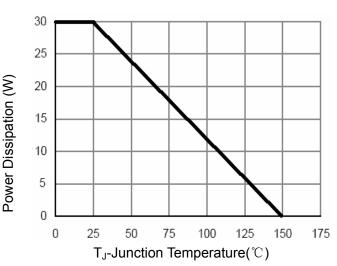
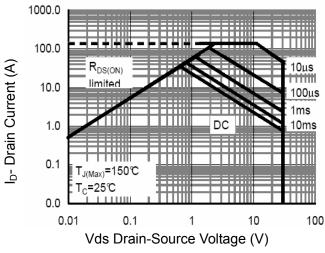


Figure 9 Power De-rating



**Figure 8 Safe Operation Area** 

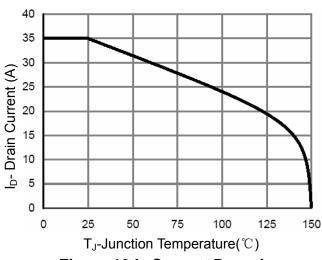
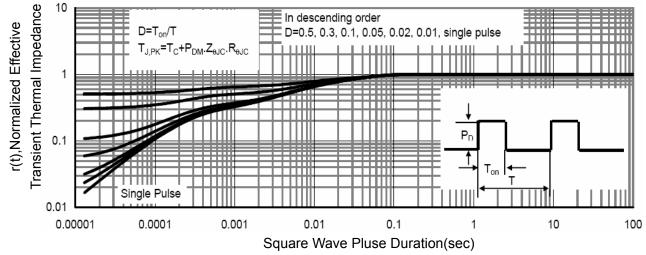


Figure 10 I<sub>D</sub> Current De-rating

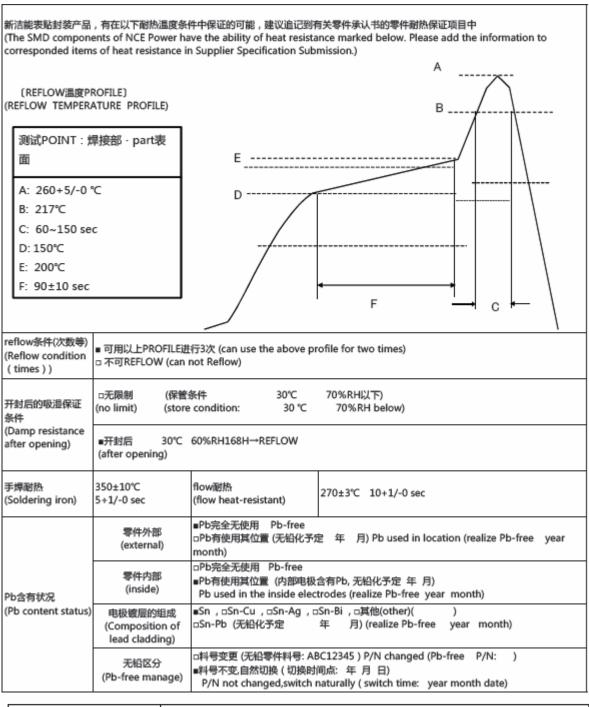


**Figure 11 Normalized Maximum Transient Thermal Impedance** 



### **Reflow Curve**

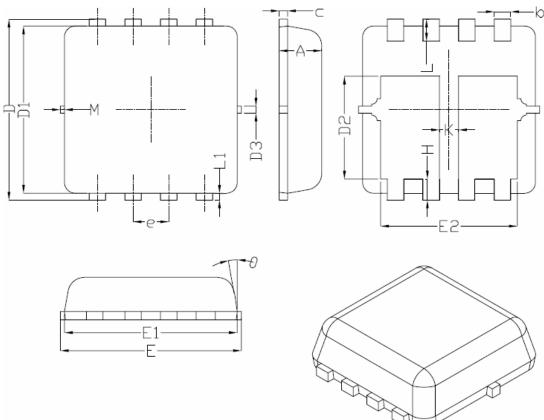
#### The Guarantee Letter of Parts Heat Resistance



| Solder Dip | 260°C /10Sec Whole body |
|------------|-------------------------|
|------------|-------------------------|

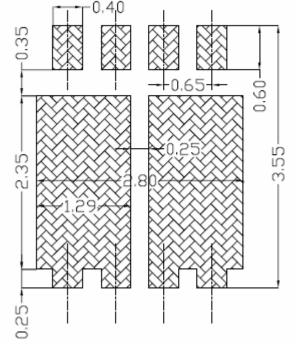


### **DFN3.3X3.3-8L Package Information**



Land Pattern (Only for Reference)

| SYMBOL | DIMENSIONAL REQMTS |         |      |
|--------|--------------------|---------|------|
|        | MIN                | NOM     | MAX  |
| A      | 0.70               | 0.75    | 0.80 |
| b      | 0.25               | 0.30    | 0.35 |
| С      | 0.10               | 0.15    | 0.25 |
| D      | 3.25               | 3.35    | 3.45 |
| D1     | 3.00               | 3.10    | 3.20 |
| D2     | 1.78               | 1.88    | 1.98 |
| D3     |                    | 0.13    |      |
| E      | 3.20               | 3.30    | 3.40 |
| EI     | 3.00               | 3.15    | 3.20 |
| E2     | 2.39               | 2.49    | 2.59 |
| e      |                    | 0.65BSC |      |
| H      | 0.30               | 0.39    | 0.50 |
| L      | 0.30               | 0.40    | 0.50 |
| L1     |                    | 0.13    |      |
| K      | 0.30               |         |      |
| θ      |                    | 10°     | 12°  |
| M      | *                  | *       | 0.15 |



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# NCE30ND35Q

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